

Application Serial No. 10/764,904
Reply to office action of May 20, 2005

PATENT
Docket: CU-3554

REMARKS/ARGUMENTS

Reconsideration is respectfully requested.

Claims 1-48 are pending in the present application before this amendment. By the present amendment, claim 9 has been amended. No new matter has been added.

The title stands objected to. In response, the examiner's suggested amendment to title has been made.

In the office action, claims 1-3 and 6-8 stand rejected under 35 U.S.C. § 102(e) as being anticipated by U.S. Patent No. 6,841,413 (Liu). The "et al." suffix in a reference name is omitted in this paper.

The examiner cites Liu to reject claim 1; however, it appears that the examiner has misinterpreted the buildup layer 154 (see Fig. 10A) in Liu col. 6, lines 64-66. According to the teachings in Liu col. 6, lines 64-66, it is evident that the first level of the build-up layer(s) 154 includes the dielectric layer 126, which may be considered similar to the dielectric interposer 3 of this invention (see Fig. 4), and the conductive trace 136 (see Figs. 6B, and 7-9), which may be considered similar to the conductive strip 4 of this invention, and that the second level of the build-up layer(s) 154 includes the dielectric layer 138 and the conductive trace 142. Hence, the entire structure of the build-up layer(s) 154 of the cited Liu reference does **not** teach or disclose the claimed conductive contact 11 (see Fig. 4) as recited in claim 1 of the present application, and the dielectric layer 126 of the cited Liu reference is **not** formed with the contact-through-hole 30 as recited in claim 1 of this application.

For the reasons above, withdrawal of rejections as to claims 1-3 and 6-8 is respectfully requested.

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In the office action, claims 9-10 stand rejected under 35 U.S.C. § 102(e) as being anticipated by U.S. Patent Application Publication No. 2004/0041271 (Storli).

In response, claim 9 has been amended to further limit the conductive strip 4 (see Figs. 15 and 16) to one in which it is directly formed on the pad-mounting surface 20 and the die-mounting surface 10.

Based on the teaching of Fig. 1C of the cited Storli reference, the conductive strip 50 is formed directly on the pad-mounting surface, but indirectly on the die-mounting surface, which is different from that of the claimed conductive strip 4 recited in claim 9 of this application. Hence, the applicant respectfully submits that the semiconductor device according to claims 9-10 is distinguishable from Storli.

In the office action, claims 4-5 and 11 are indicated as being allowable if they are written to include all limitations of the base claim and any intervening claims.

In the office action, claims 12-21 stand allowed.

The office action of May 20, 2005 incorrectly indicates claims 1-21 as being currently pending. It is respectfully noted that the original claims 1-48 have been presented in the specification of the present application. Accordingly, the applicant respectfully requests prompt examination of claims 22-48 and solicit allowance of these claims in the next action. Further, a final rejection status in the next action if the action rejects any of claims 22-48 would be improper, since these unexamined claims are being examined for the first time.

For the reasons set forth above, the applicant respectfully submits that claims 1-48, pending in this application, are in condition for allowance over the cited references. Accordingly, the applicant respectfully requests reconsideration and withdrawal of the

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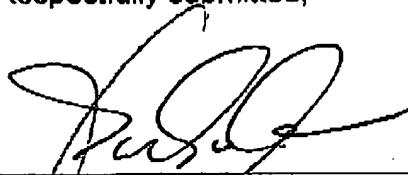
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outstanding rejections and earnestly solicits an indication of allowable subject matter.

This amendment is considered to be responsive to all points raised in the office action.

Should the Examiner have any remaining questions or concerns, the Examiner is encouraged to contact the undersigned attorney by telephone to expeditiously resolve such concerns.

Respectfully submitted,



Dated: October 7, 2005

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